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**Vishay Siliconix** 

# Automotive P-Channel 60 V (D-S) 175 °C MOSFET



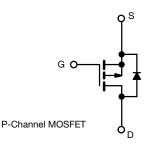
Marking code: Q021

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	-60			
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS}$ = -10 V	0.065			
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS}$ = -4.5 V	0.090			
I <sub>D</sub> (A)	-16			
Configuration	Single			
Package	PowerPAK 1212-8W			

#### **FEATURES**

- TrenchFET<sup>®</sup> power MOSFET
- Low thermal resistance PowerPAK<sup>®</sup> 1212-8W package with 1.07 mm profile
- AEC-Q101 qualified
- Wettable flank terminals
- 100 % R<sub>g</sub> and UIS tested
- Material categorization:

for definitions of compliance www.vishay.com/doc?99912





#### RoHS COMPLIANT HALOGEN FREE

please see

PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-source voltage	V <sub>DS</sub>	-60	v	
Gate-source voltage		V <sub>GS</sub> ± 20	± 20	v
Continuous drain current	T <sub>C</sub> = 25 °C <sup>a</sup>	- I <sub>D</sub>	-16	
Continuous drain current	T <sub>C</sub> = 125 °C		-11	
Continuous source current (diode conduction) <sup>a</sup>		I <sub>S</sub>	-16	А
Pulsed drain current <sup>b</sup>		I <sub>DM</sub>	-64	1
Single pulse avalanche current		I <sub>AS</sub>	-23	
ingle pulse avalanche energy		E <sub>AS</sub>	26	mJ
Maximum power dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	P <sub>D</sub>	53	W
Maximum power dissipation 5	T <sub>C</sub> = 125 °C		17	
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	℃
Soldering recommendations (peak temperature) <sup>d</sup>			260	

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	LIMIT	UNIT		
Junction-to-ambient	PCB Mount <sup>c</sup>	R <sub>thJA</sub>	81	°C/W	
Junction-to-case (drain)		R <sub>thJC</sub>	2.8	0/11	

#### Notes

a. Package limited

b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %

c. When mounted on 1" square PCB (FR4 material)

d. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components

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PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static					•		
Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub> =	= 0 V, I <sub>D</sub> = -250 μA	-60	-	-	v
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	V <sub>GS</sub> , I <sub>D</sub> = -250 μA	-1.5	-2.0	-2.5	
Gate-source leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	0 V, $V_{GS} = \pm 20$ V	-	-	± 100	nA
		$V_{GS} = 0 V$	V <sub>DS</sub> = -60 V	-	-	-1	
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = -60 V, T <sub>J</sub> = 125 °C	-	-	-50	μA
		$V_{GS} = 0 V$	V <sub>DS</sub> = -60 V, T <sub>J</sub> = 175 °C	-	-	-150	
On-state drain current <sup>a</sup>	I <sub>D(on)</sub>	$V_{GS} = -10 V$	$V_{DS} \le -5 V$	-15	-	-	Α
		$V_{GS} = -10 V$	I <sub>D</sub> = -5.7 A	-	0.050	0.065	
	R <sub>DS(on)</sub>	$V_{GS} = -10 V$	I <sub>D</sub> = -5.7 A, T <sub>J</sub> = 125 °C	-	-	0.112	
Drain-source on-state resistance <sup>a</sup>	Do(on)	V <sub>GS</sub> = -10 V	I <sub>D</sub> = -5.7 A, T <sub>J</sub> = 175 °C	-	-	0.138	Ω
		$V_{GS} = -4.5 V$	I <sub>D</sub> = -4.4 A,	-	0.070	0.090	
Forward transconductance b		V <sub>DS</sub> =	-15 V, I <sub>D</sub> = -5.7 A	-	13	-	S
Dynamic <sup>b</sup>							
Input capacitance	C <sub>iss</sub>			-	1108	1385	
Output capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = -25 V, f = 1 MHz	-	132	165	pF
Reverse transfer capacitance	C <sub>rss</sub>			-	84	105	1
Total gate charge <sup>c</sup>	Qg			-	25.5	38	
Gate-source charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = -10 V	$V_{DS} = -30 \text{ V}, \text{ I}_{D} = -5.7 \text{ A}$	-	3.6	-	nC
Gate-drain charge <sup>c</sup>	Q <sub>gd</sub>			-	6.7	-	
Gate resistance	Rg		f = 1 MHz	3	6	9	Ω
Turn-on delay time <sup>c</sup>	t <sub>d(on)</sub>			-	9	14	
Rise time <sup>c</sup>	t <sub>r</sub>	V <sub>DD</sub> =	= -30 V, R <sub>L</sub> = 30 Ω	-	9	14	1
Turn-off delay time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong$ -1 Å, $V_{GEN}$ = -10 V, $R_g$ = 1 $\Omega$		-	37	56	– ns
Fall time <sup>c</sup>	t <sub>f</sub>			-	8	12	
Source-drain diode ratings and chara	cteristics <sup>b</sup>						
Pulsed current <sup>a</sup>	I <sub>SM</sub>			-	-	-64	Α
Forward voltage	V <sub>SD</sub>	$I_{\rm F} = -6 \text{ A}, \text{ V}_{\rm GS} = 0 \text{ V}$		_	-0.85	-1.2	V

#### Notes

a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %

b. Guaranteed by design, not subject to production testing

c. Independent of operating temperature

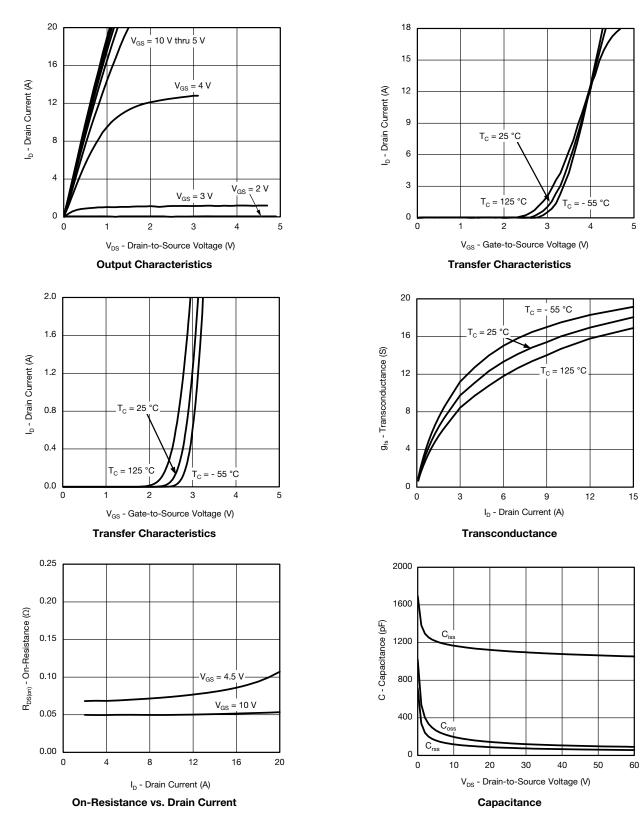
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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## **TYPICAL CHARACTERISTICS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)



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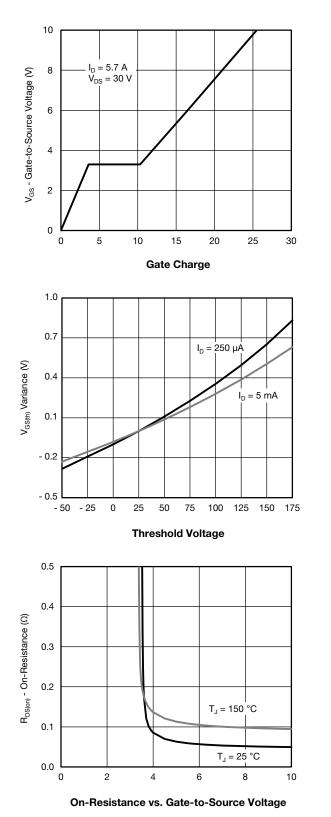
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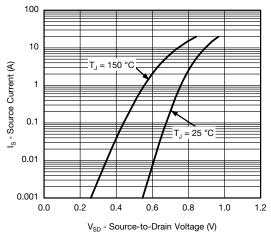
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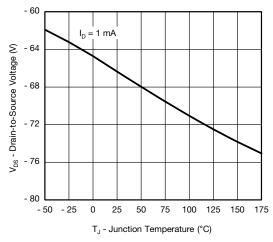
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T<sub>J</sub> - Junction Temperature (°C)

**On-Resistance vs. Junction Temperature** 



Source Drain Diode Forward Voltage



Drain Source Breakdown vs. Junction Temperature

S20-0765, Rev. B, 12-Oct-2020

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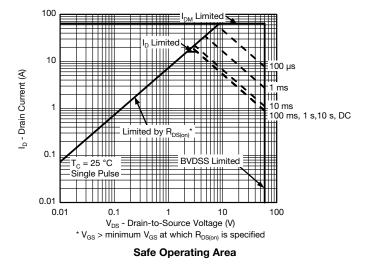
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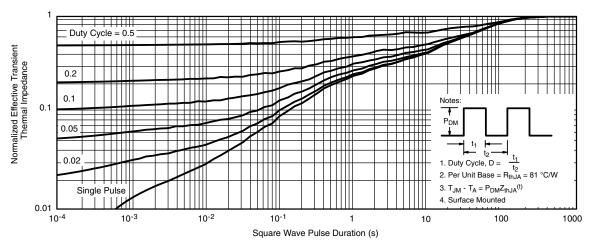
## **THERMAL RATINGS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)



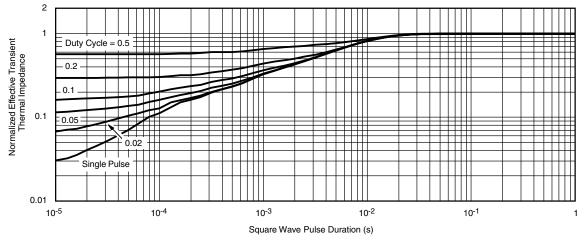


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### **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

• The characteristics shown in the two graphs

- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

- Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

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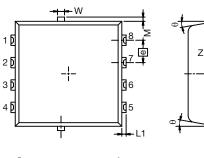


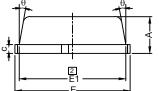
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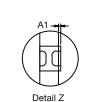
# PowerPAK<sup>®</sup> 1212-8W Case Outline

Δ2

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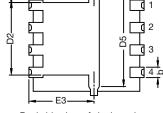




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Б



E2

E4

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Notes
1 Inch will govern

 Dimensions exclusive of mold gate burrs
 Dimensions exclusive of mold flash and cutting burrs

DIM.	MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	NOM. MAX.	MIN.	NOM.	MAX.	
А	0.97	1.04	1.12	0.038	0.041	0.044	
A1	0	-	0.05	0	-	0.002	
A2	0	-	0.13	0	-	0.005	
b	0.23	0.30	0.41	0.009	0.012	0.016	
С	0.23	0.28	0.33	0.009	0.011	0.013	
D	3.20	3.30	3.40	0.126	0.130	0.134	
D1	2.95	3.05	3.15	0.116	0.120	0.124	
D2	1.98	2.11	2.24	0.078	0.083	0.088	
D4	0.47 typ.			0.0185 typ.			
D5	2.3 typ.			0.090 typ.			
E	3.20	3.30	3.40	0.126	0.130	0.134	
E1	2.95	3.05	3.15	0.116	0.120	0.124	
E2	1.47	1.60	1.73	0.058	0.063	0.068	
E3	1.75	1.85	1.98	0.069	0.073	0.078	
E4	0.34 typ.				0.013 typ.		
е		0.65 BSC.		0.026 BSC			
К		0.86 typ.		0.034 typ.			
Н	0.30	0.41	0.51	0.012	0.016	0.020	
L	0.30	0.43	0.56	0.012	0.017	0.022	
L1	0.06	0.13	0.20	0.002	0.005	0.008	
θ	0°	-	12°	0°	-	12°	
W	0.15	0.25	0.36	0.006	0.010	0.014	
М	0.125 typ.			0.005 typ.			
N: C15-1530-R	ev. B, 16-Nov-15						

Backside view of single pad



## RECOMMENDED MINIMUM PADS FOR PowerPAK<sup>®</sup> 1212-8 Single



Recommended Minimum Pads Dimensions in Inches/(mm)

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